

Amendments to the Claims

1-24. (Cancel)

25. (New) A heat-treating method for a packaging product, comprising:
providing a packaging product formed by enclosing a content material within a packaging material comprising at least a layer of hydrophilic resin, and
heat-treating the packaging product with hot water,
wherein the hot water is caused to contain a water-soluble compound.

26. (New) A heat-treating method according to Claim 25, wherein the hot water has a temperature of 60-100°C to effect a boiling heat-treatment.

27. (New) A heat-treating method according to Claim 25, wherein the hot water has a temperature exceeding 100°C to effect a retort heat-treatment.

28. (New) A heat-treating method according to Claim 25, wherein the hot water contains the water-soluble compound at a concentration exceeding 0.1 wt.%.

29. (New) A heat-treating method according to Claim 25, wherein the hot water contains the water-soluble compound at a concentration of at least 1 wt.%.

30. (New) A heat-treating method according to Claim 25, wherein the water-soluble compound is an inorganic electrolyte.

31. (New) A heat-treating method according to Claim 30, wherein the water-soluble compound is a water-soluble inorganic salt.

32. (New) A heat-treating method according to Claim 31, wherein the water-soluble compound is a chloride selected from the group consisting of sodium chloride, magnesium chloride, and potassium chloride.

33. (New) A heat-treating method according to Claim 32, wherein the water-soluble compound is sodium chloride.
34. (New) A heat-treating method according to Claim 25, wherein the water-soluble compound is a water-soluble organic compound.
35. (New) A heat-treating method according to Claim 34, wherein the water-soluble compound is a water-soluble alcohol.
36. (New) A heat-treating method according to Claim 25, wherein the hydrophilic resin layer is a gas-barrier resin layer.
37. (New) A heat-treating method according to Claim 36, wherein the gas-barrier resin is selected from the group consisting of ethylene-vinyl alcohol copolymer, polyamide (co-)polymers, and aliphatic ester (co-)polymers.
38. (New) A heat-treating method according to Claim 37, wherein the gas-barrier resin is selected from the group consisting ethylene-vinyl alcohol copolymer, polymetaxylylene adipamide and glycolic acid (co-)polymer.
39. (New) A heat-treating method according to Claim 25, wherein the packaging material has a multi-layer structure.
40. (New) A heat-treating method according to Claim 39, wherein the hydrophilic resin layer is disposed as a surface layer contacting the hot water of the packaging material.
41. (New) A heat-treating method according to Claim 39, wherein the hydrophilic resin layer is disposed as an inner layer not directly contacting the hot water of the packaging material.

42. (New) A heat-treating method according to Claim 41, wherein the gas-barrier resin is glycolic acid (co-)polymer.
43. (New) A packaged product, which has been heat-treated by a heat-treating method according to Claim 25.
44. (New) A packaged product according to Claim 43, wherein the heat-treated packaging material has a haze below 20%.
45. (New) A heat-treated packaged product, comprising a heat-treated packaging material having a multi-layer structure including an inner layer of a hydrophilic gas-barrier resin layer selected from the group consisting of ethylene-vinyl alcohol copolymer and glycolic acid (co-)polymer, and a content material enclosed within the packaging material, wherein the heat-treated packaging material has a haze below 20%.
46. (New) A packaged product according to Claim 45, wherein the hydrophilic gas-barrier resin is ethylene-vinyl alcohol copolymer.
47. (New) A packaged product according to Claim 45, wherein the hydrophilic gas-barrier resin is glycolic acid (co-)polymer.
48. (New) A packaged product according to Claim 43, wherein the packaged material has been subjected to a heat-shrinking treatment during the heat treatment.